

Global SiC Wafer Laser Cutting Equipment Supply, Demand and Key Producers, 2023-2029

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Abstracts

The global SiC Wafer Laser Cutting Equipment market size is expected to reach \$ 257.8 million by 2029, rising at a market growth of 15.6% CAGR during the forecast period (2023-2029).

Global key players of SiC wafer laser cutting equipment include DISCO Corporation, SuZhou Delphi Laser and Han's Laser, etc. The top three players hold a share over 60%. From the perspective of consumption value by region, Asia-Pacific (excluding China) is the largest market of SiC wafer laser cutting equipment, followed by China, North America, and Europe. In terms of type, processing sizes up to 6 Inches account for more than 75% of the market share. In terms of application, foundry has a share over 60 %.

Silicon carbide (SiC) was discovered in 1893 as an industrial abrasive for grinding wheels and automotive brakes. The scheme of laser cutting silicon carbide is laser modified cutting technology. The principle is to use a laser beam with a high transmission wavelength to focus on the inside of the wafer through a lens, and multiphoton absorption occurs, resulting in a local deformation layer, namely modified layer. The layer is mainly composed of holes, high dislocation density layers and cracks. The modified layer is the starting point of subsequent wafer dicing and cracking. The modified layer can be confined inside the wafer by optimizing the laser and optical path system, and no thermal damage is caused to the surface and bottom of the wafer. Then, use external force to guide the cracks to the surface and bottom of the wafer, separating the wafer into the required size.

This report studies the global SiC Wafer Laser Cutting Equipment production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for SiC Wafer Laser Cutting Equipment, and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2022 as the base year. This report explores demand trends and competition, as well as details the characteristics of SiC Wafer Laser Cutting Equipment that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global SiC Wafer Laser Cutting Equipment total production and demand, 2018-2029, (Units)

Global SiC Wafer Laser Cutting Equipment total production value, 2018-2029, (USD Million)

Global SiC Wafer Laser Cutting Equipment production by region & country, production, value, CAGR, 2018-2029, (USD Million) & (Units)

Global SiC Wafer Laser Cutting Equipment consumption by region & country, CAGR, 2018-2029 & (Units)

U.S. VS China: SiC Wafer Laser Cutting Equipment domestic production, consumption, key domestic manufacturers and share

Global SiC Wafer Laser Cutting Equipment production by manufacturer, production, price, value and market share 2018-2023, (USD Million) & (Units)

Global SiC Wafer Laser Cutting Equipment production by Type, production, value, CAGR, 2018-2029, (USD Million) & (Units)

Global SiC Wafer Laser Cutting Equipment production by Application production, value, CAGR, 2018-2029, (USD Million) & (Units)

This reports profiles key players in the global SiC Wafer Laser Cutting Equipment market based on the following parameters – company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include DISCO Corporation, Suzhou Delphi Laser Co, Han's Laser Technology, 3D-Micromac, Synova S.A., HGTECH, ASMPT, GHN.GIE and Wuhan DR Laser Technology, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals, COVID-19 and Russia-Ukraine War Influence.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World SiC Wafer Laser Cutting Equipment market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), volume (production, consumption) & (Units) and average price (US\$/Unit) by manufacturer, by Type, and by Application. Data is given for the years 2018-2029 by year with 2022 as the base year, 2023 as the estimate year, and 2024-2029 as the forecast year.

Global SiC Wafer Laser Cutting Equipment Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global SiC Wafer Laser Cutting Equipment Market, Segmentation by Type

Processing Sizes up to 6 Inches

Processing Sizes up to 8 Inches

Global SiC Wafer Laser Cutting Equipment Market, Segmentation by Application

Foundry

IDM

Companies Profiled:

DISCO Corporation

Suzhou Delphi Laser Co

Han's Laser Technology

3D-Micromac

Synova S.A.

HGTECH

ASMPT

GHN.GIE

Wuhan DR Laser Technology

Key Questions Answered

1. How big is the global SiC Wafer Laser Cutting Equipment market?
2. What is the demand of the global SiC Wafer Laser Cutting Equipment market?
3. What is the year over year growth of the global SiC Wafer Laser Cutting Equipment market?

4. What is the production and production value of the global SiC Wafer Laser Cutting Equipment market?
5. Who are the key producers in the global SiC Wafer Laser Cutting Equipment market?
6. What are the growth factors driving the market demand?

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